

**80V N-Ch Power MOSFET**
**Feature**

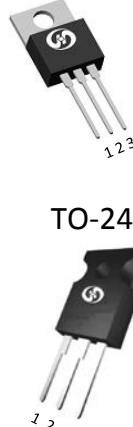
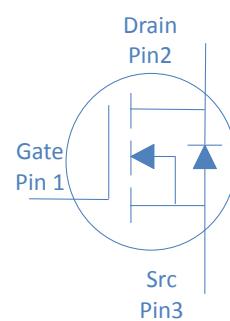
- ◊ High Speed Power Smooth Switching
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free

**Application**

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ Power Tools
- ◊ UPS
- ◊ Motor Control

$V_{DS}$	80	V
$R_{DS(on),typ}$	TO-263	2.9 mΩ
$R_{DS(on),typ}$	TO-247	3.1 mΩ
$R_{DS(on),typ}$	TO-220	3.2 mΩ
$I_D$ (Silicon Limited)	187	A
$I_D$ (Package Limited)	120	A

**TO-263**

**TO-220**

**TO-247**


Part Number	Package	Marking
HGB039N08S	TO-263	GB039N08S
HGK039N08S	TO-247	GK039N08S
HGP039N08S	TO-220	GP039N08S

**Absolute Maximum Ratings at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C=25^\circ\text{C}$	187	A
Continuous Drain Current (Package Limited)		$T_C=100^\circ\text{C}$	132	
		$T_C=25^\circ\text{C}$	120	
Drain to Source Voltage	$V_{DS}$	-	80	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	500	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.4\text{mH}, T_C=25^\circ\text{C}$	720	mJ
Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	250	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 175	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{\Theta JC}$	0.6	°C/W
Thermal Resistance Junction-Ambient	$R_{\Theta JA}$	60	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

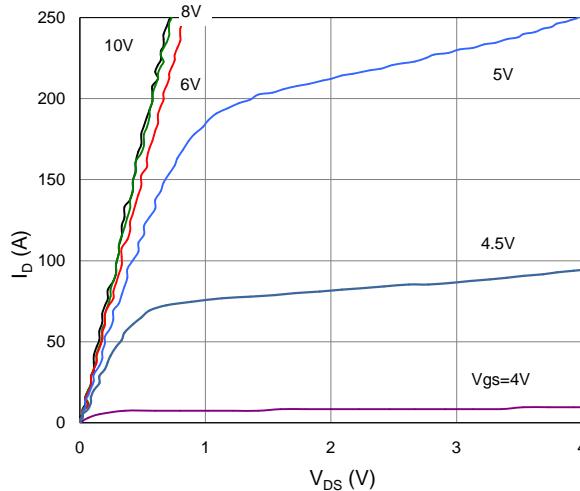
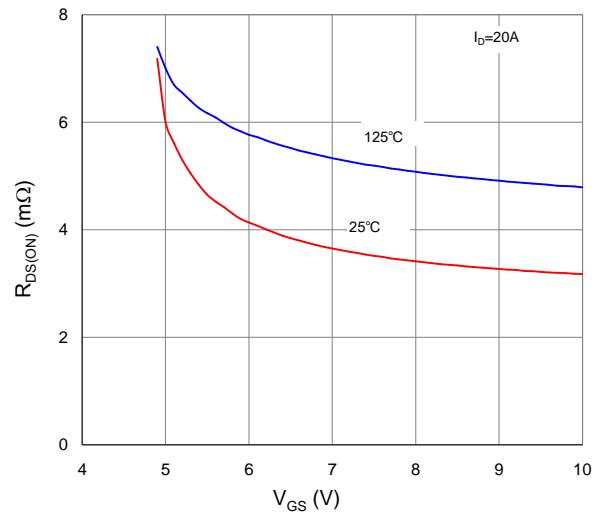
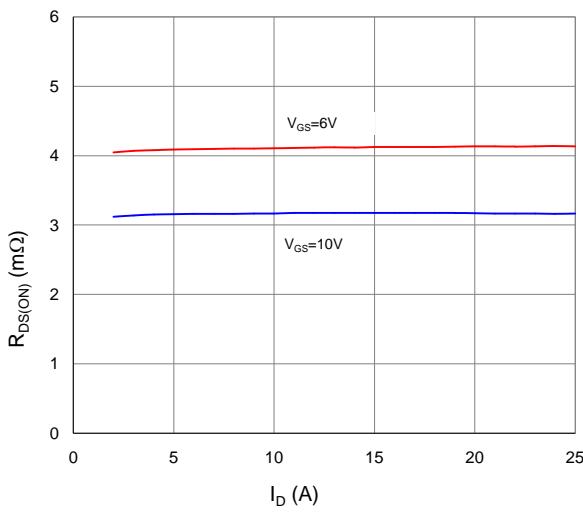
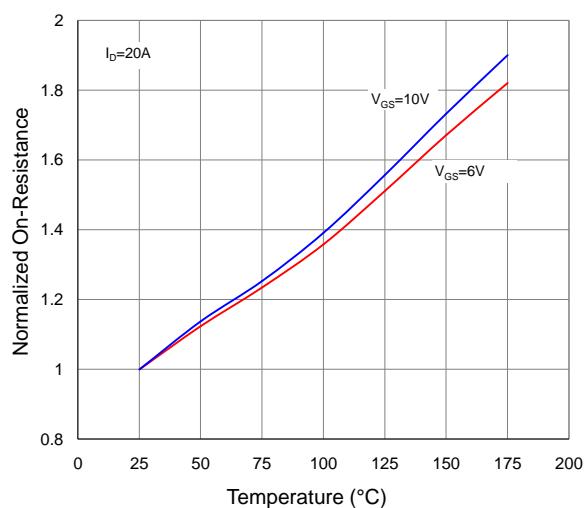
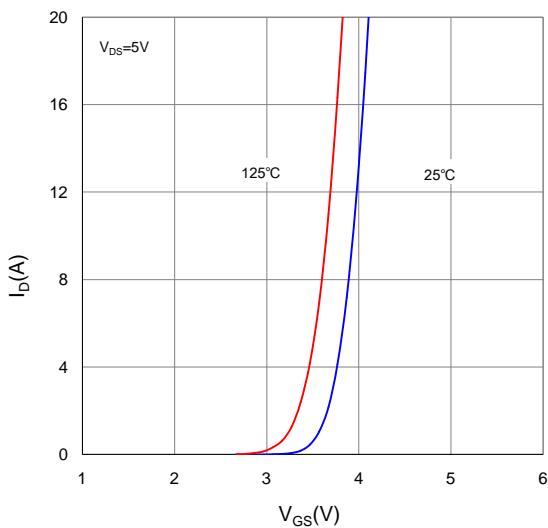
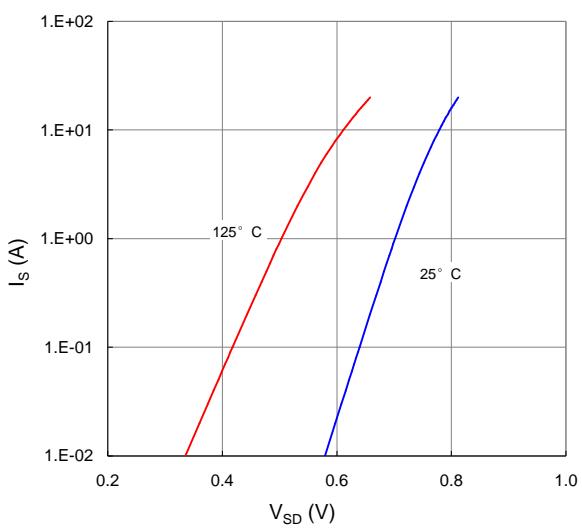
Parameter	Symbol	Conditions	Value			Unit	
			min	typ	max		
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	80	-	-	V	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	2	3	4		
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$	
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}, T_j=100^\circ\text{C}$	-	-	100		
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA	
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=20\text{A}$	TO-263	-	2.9	3.6	$\text{m}\Omega$
			TO-247		3.1	3.8	
			TO-220	-	3.2	3.9	
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_D=20\text{A}$	-	70	-	S	
Gate Resistance	$R_G$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	0.7	-	$\Omega$	

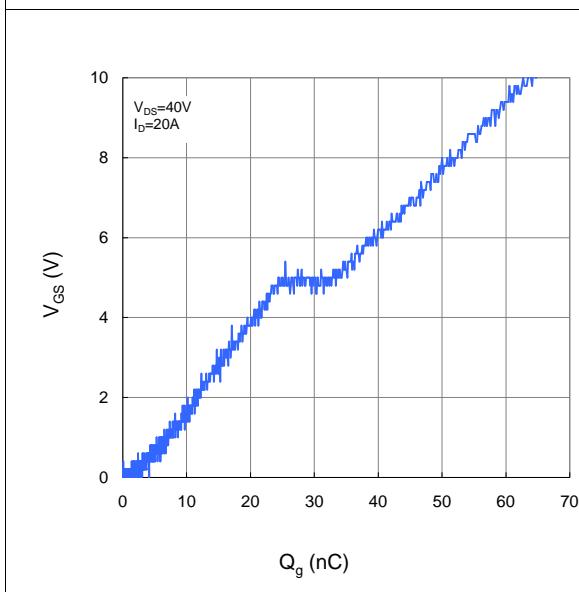
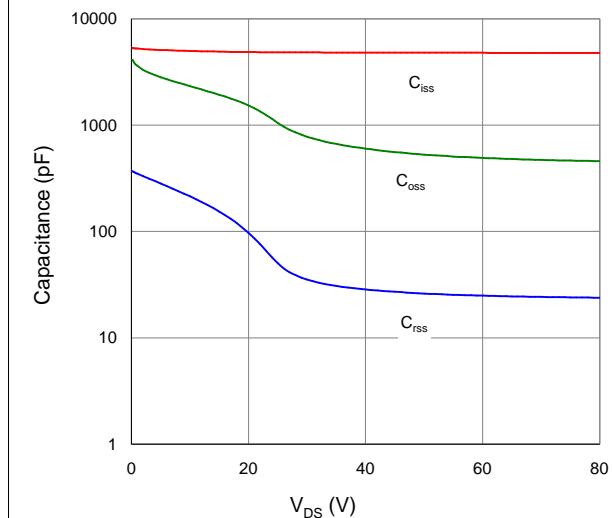
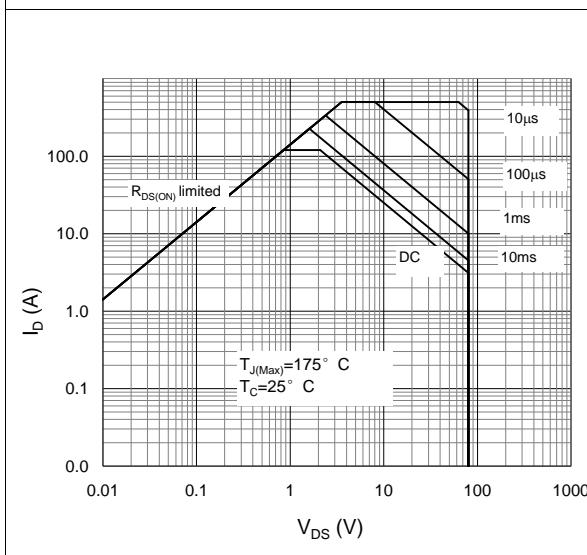
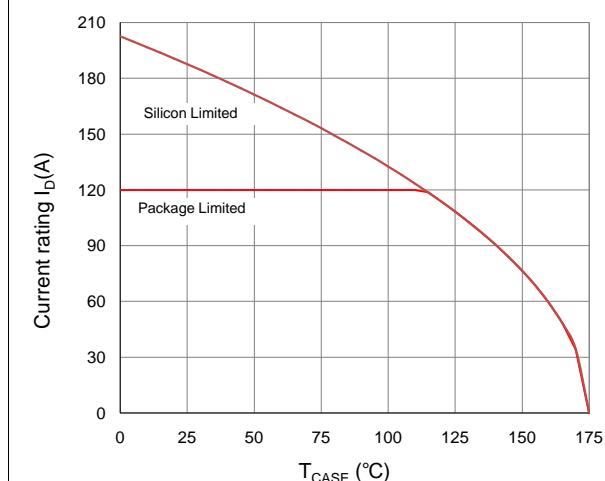
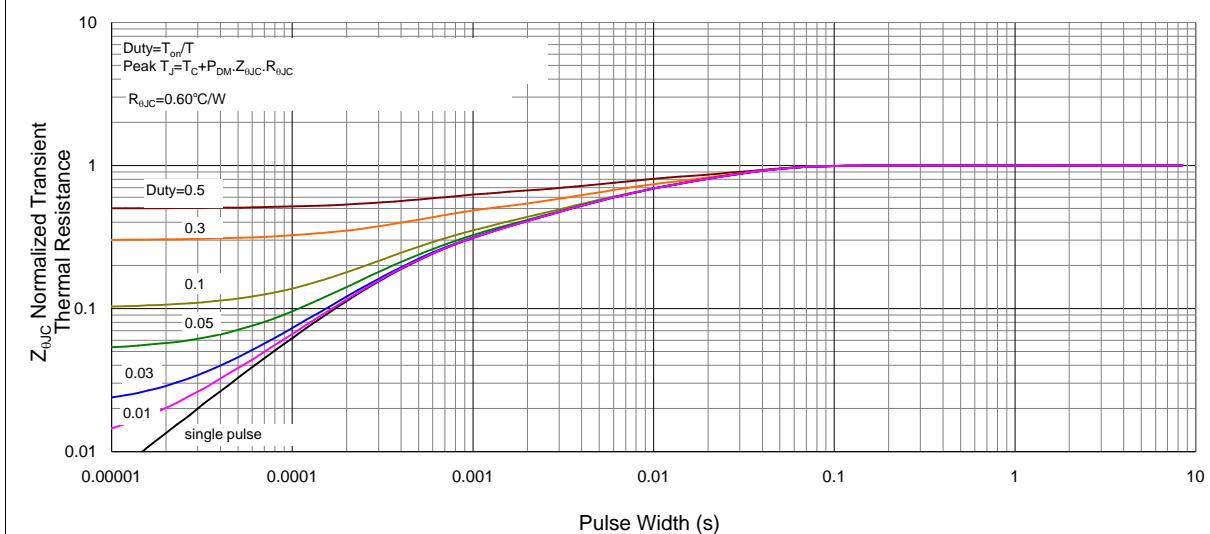
**Dynamic Characteristics**

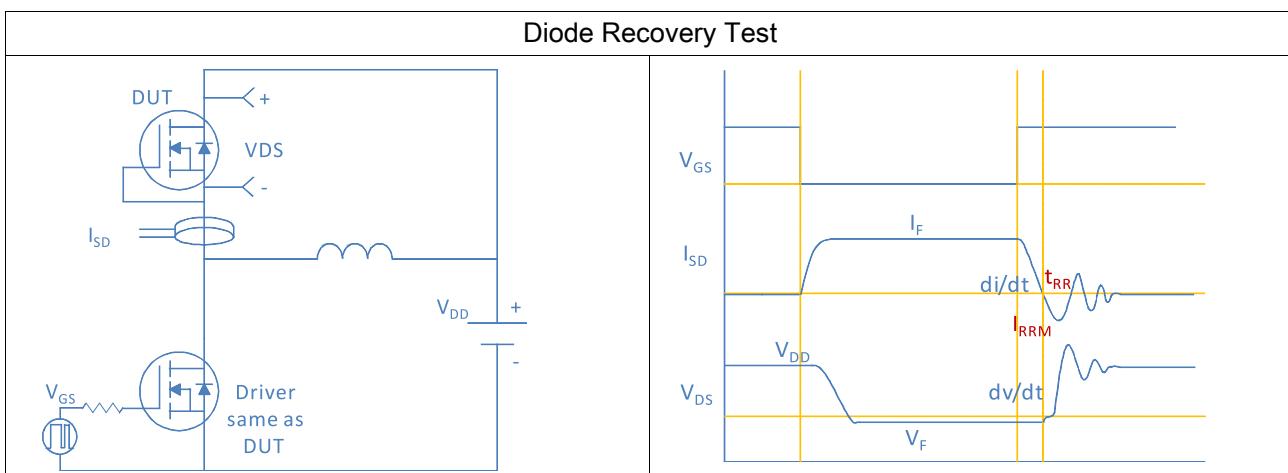
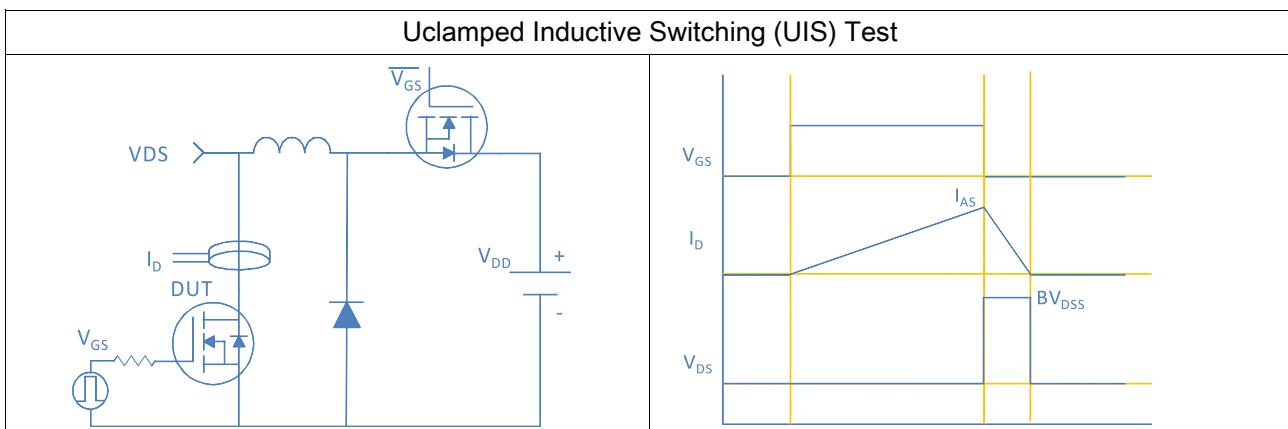
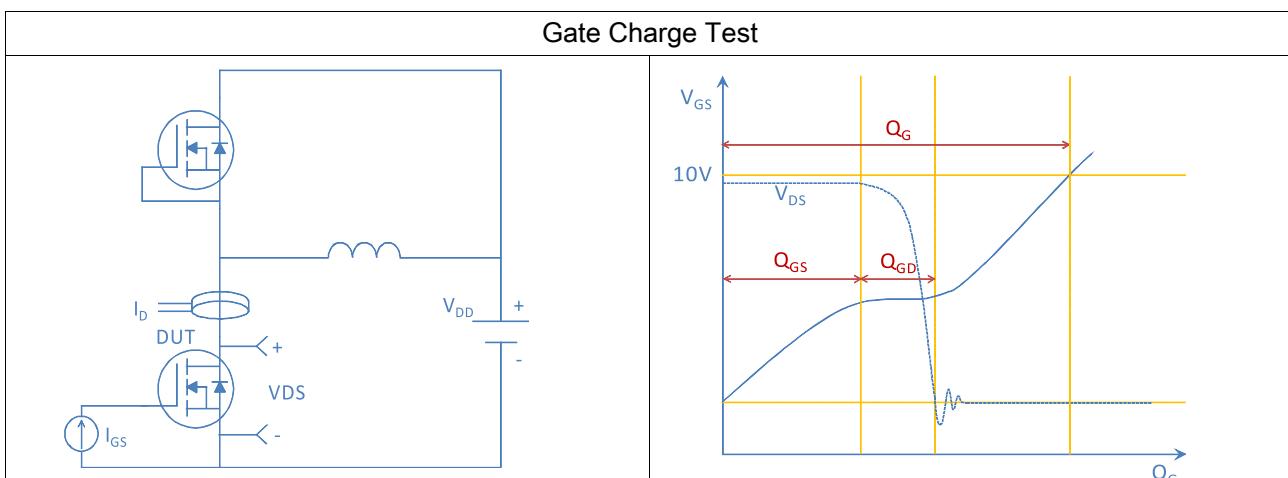
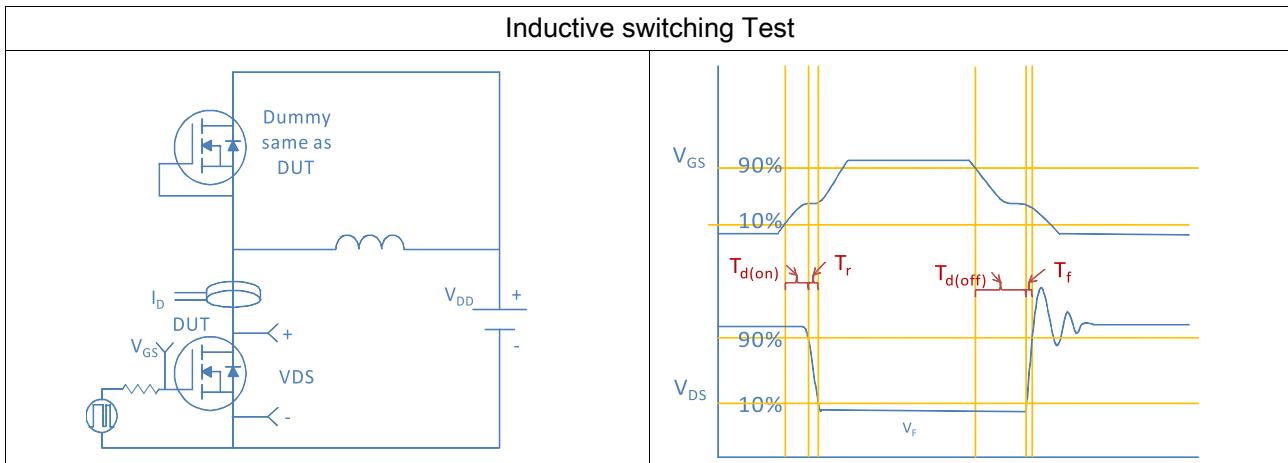
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=40\text{V}, f=1\text{MHz}$	-	4820	-	pF
Output Capacitance	$C_{\text{oss}}$		-	602	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	28.5	-	
Total Gate Charge	$Q_g$	$V_{\text{DD}}=40\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}$	-	64	-	nC
Gate to Source Charge	$Q_{\text{gs}}$		-	24	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	9	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=40\text{V}, I_D=20\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	19	-	ns
Rise time	$t_r$		-	13	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	50	-	
Fall Time	$t_f$		-	9	-	

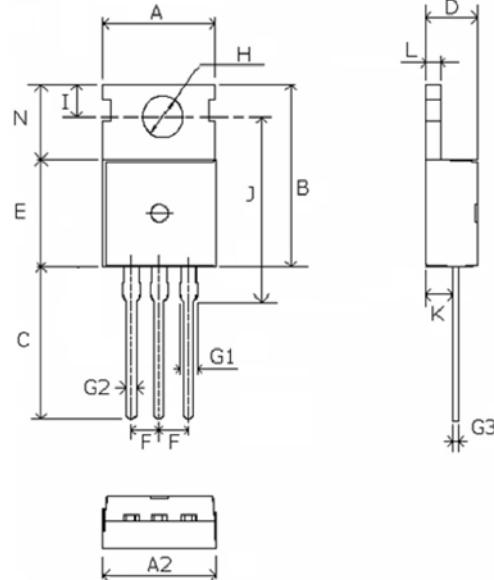
**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R=40\text{V}, I_F=20\text{A}, dI_F/dt=400\text{A}/\mu\text{s}$	-	50	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	200	-	nC

**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


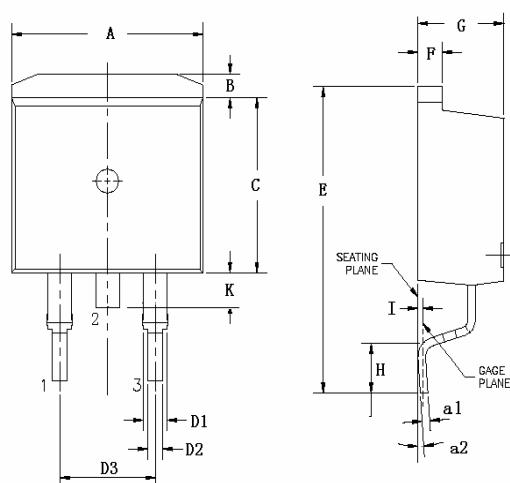
**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case**




**TO-220, 3 leads**


Dimensions in mm unless otherwise specified

Symbol	Min	Nom	Max
A	9.66	9.97	10.28
A2	9.80	10.00	10.20
B	15.60	15.70	15.80
C	12.70	13.48	14.27
D	4.30	4.50	4.70
E	9.00	9.20	9.40
F		2.54	
G1	1.32	1.52	1.72
G2	0.70	0.82	0.95
G3	0.45	0.52	0.60
H	3.50	3.60	3.70
I	2.70	2.80	2.90
J	15.70	15.97	16.25
K	2.20	2.40	2.60
L	1.15	1.27	1.40
N	6.40	6.60	6.80

**TO-263, 2 leads**


Dimensions in mm unless otherwise specified

Symbol	Min	Nom	Max
A	9.66	9.97	10.28
B	1.02	1.17	1.32
C	8.59	9.00	9.40
D1	1.14	1.27	1.40
D2	0.70	0.83	0.95
D3		5.08	
E	15.09	15.24	15.39
F	1.15	1.28	1.40
G	4.30	4.50	4.70
H	2.29	2.54	2.79
I		0.25	
K	1.30	1.45	1.60
a1	0.45	0.55	0.65
a2(degree)	0°		8°

**TO-247, 3 leads**
